

**IN THE CLAIMS:**

This listing of the claims replaces all prior versions and listings of the claims in this application.

The text of all pending claims (including any withdrawn claims) is set forth below. Canceled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with strikethrough. The status of each claim is indicated with one of (Original), (Currently amended), (Canceled), (Withdrawn), (Previously presented), (New), and (Not entered).

Please AMEND claim 14 in accordance with the following:

1. (Withdrawn) A deposition mask frame assembly comprising:  
a mask comprising a thin plate in which a predetermined pattern of apertures is formed;  
a frame supporting one surface of the mask so that the mask is tensed; and  
a cover mask supporting an opposite surface of the mask, wherein the cover mask corresponds to the frame.
2. (Withdrawn) The deposition mask frame assembly of claim 1, wherein the mask is formed of nickel or an alloy of nickel and cobalt.
3. (Withdrawn) The deposition mask frame assembly of claim 2, wherein the mask is formed by electro-forming.
4. (Withdrawn) The deposition mask frame assembly of claim 1, wherein the mask, the frame, and the cover mask are joined together by welding.
5. (Withdrawn) The deposition mask frame assembly of claim 4, wherein the welding is a dot welding.
6. (Canceled)

7. (Withdrawn) The deposition mask frame assembly of claim 1, wherein the cover mask is configured so as to support the four edges of the mask.

8. (Withdrawn) A method of manufacturing a deposition mask frame assembly, the method comprising:

electrodepositing a metal on an electrodepositing plate using an electro-forming method, wherein the metal is electrodeposited to a predetermined thickness, and the electrodepositing plate has a film attached corresponding to shielding portions that form an outer portion of a mask and define apertures in the mask;

separating the mask from the electrodepositing plate; and

installing a frame on one surface of the mask and installing a cover mask on the other surface of the mask while the mask is being tensed, and welding the cover mask, the mask, and the frame.

9. (Withdrawn) The method of claim 8, wherein the predetermined thickness is 30-50 $\mu$ m.

10. (Withdrawn) The method of claim 8, wherein the mask comprises nickel or an alloy of nickel and cobalt.

11. (Withdrawn) The method of claim 8, wherein the inner circumference of the cover mask is larger than an outer circumference of a substrate on which a layer is deposited.

12. (Withdrawn) The method of claim 8, wherein different tensions are applied to different sides of the mask to reduce a deviation of a total pitch of apertures and a line deviation.

13. (Withdrawn) The method of claim 8, wherein a portion of the cover mask and an edge of the mask are cut off to match a size and shape of the mask and the cover mask with the frame.

14. (Currently amended) A method of manufacturing an organic EL device, the method comprising:

forming a first electrode layer in a predetermined pattern on an insulating substrate;  
forming an organic film comprising at least a patterned emission layer on the first

electrode layer; and

forming a second electrode layer in a predetermined pattern on the organic film; and  
~~sealing the second electrode layer;~~

wherein the organic film and/or the second electrode layer are/is deposited using a deposition mask frame assembly, the deposition mask frame assembly comprising:

a flat mask comprising a flat thin plate in which a predetermined pattern of apertures is formed, the flat mask having a first flat surface extending over an entire area of the flat mask, and a second flat surface extending over the entire area of the flat mask, the second flat surface being separated from the first flat surface by a thickness of the mask;

a flat frame supporting the first flat surface of the flat mask so that the flat mask is tensed and the first flat surface remains flat; and

a flat cover mask supporting the second flat surface of the flat mask so that the second flat surface remains flat.

15. (Previously presented) The method of claim 14, wherein the flat mask is formed of nickel or an alloy of nickel and cobalt.

16. (Previously presented) The method of claim 14, wherein the flat mask is a flat electro-formed mask.

17. (Previously presented) The method of claim 14, wherein the flat mask, the flat frame, and the flat cover mask are held together by welds.

18. (Previously presented) The method of claim 17, wherein the welds are dot welds.

19. (Previously presented) The method of claim 18, wherein a welding pitch between the dot welds is 3 mm or less.

20. (Canceled)

21. (Previously presented) The method of claim 14, wherein the flat mask is tensed with different tensions at different points on each of a plurality of sides of the flat mask.

22. (Previously presented) The method of claim 14, wherein the flat frame and the flat cover mask are the only elements that touch the flat mask.